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## PATENT APPLICATION

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q95609

Toyoaki ISHIWATA, et al.

Appln. No.: 10/584,330

Group Art Unit: to be assigned

Confirmation No.: 9644

Examiner: to be assigned

Filed: June 26, 2006

For: LAMINATE

## SUBMISSION OF TRANSLATION OF INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

## MAIL STOP AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Applicants submit herewith for the Examiner's use an English language translation of the International Preliminary Report on Patentability for PCT/JP2004/019688 dated September 14, 2006. A foreign language version of the International Preliminary Report on Patentability was submitted with the Information Disclosure Statement filed on September 26, 2006.

Respectfully submitted,

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Date: April 5, 2007

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Registration No. 33,725

## PATENT COOPERATION TREATY

## From the INTERNATIONAL BUREAU

## **PCT**

NOTIFICATION OF TRANSMITTAL
OF COPIES OF TRANSLATION
OF THE INTERNATIONAL PRELIMINARY REPORT
ON PATENTABILITY
(CHAPTER I OR CHAPTER II
OF THE PATENT COOPERATION TREATY)

(PCT Rules 44bis.3(c) and 72.2)

To:

OHSHIMA, Masataka
Ohshima Patent Office
Fukuya Bldg.
3, Yotsuya 4-chome
Shinjuku-ku, Tokyo 160-0004
JAPON



Date of mailing (day/month/year) 14 September 2006 (14.09.2006)	
Applicant's or agent's file reference G281TJ	IMPORTANT NOTIFICATION
International application No. PCT/JP2004/019688	International filing date (day/month/year) 22 December 2004 (22.12.2004)
Applicant	TEIJIN LIMITED et al

1.	<b>Transmittal</b>	of the	translation	to	the applicant.
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The International Bureau transmits herewith a copy of the English translation of the international	preliminary repo	ort or
 patentability (Chapter I).		

The International Bureau transmits herewith a copy of the English translation of the international preliminary report on patentability (Chapter II).

Transmittal of the copy of the translation to the designated or elected Offices.

The International Bureau notifies the applicant that copies of that translation have been transmitted to the following designated or elected Offices requiring such translation:

EP, KR

The following designated or elected Offices, having waived the requirement for such a transmittal at this time, will receive copies of that translation from the International Bureau only upon their request:

AE, AG, AL, AM, AP, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EA, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OA, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW

3. Reminder regarding translation into (one of) the official language(s) of the elected Office(s).

The applicant is reminded that, where a translation of the international application must be furnished to an elected Office, that translation must contain a translation of any annexes to the international preliminary report on patentability (Chapter II).

It is the applicant's responsibility to prepare and furnish such translation directly to each elected Office concerned within the applicable time limit (Rule 74.1). See Volume II of the PCT Applicant's Guide for further details.

The International Bureau of WIPO 34, chemin des Colombettes 1211 Geneva 20, Switzerland Authorized officer

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Facsimile No. +41 22 338 82 70 Form PCT/IB/338 (January 2004)

## PATENT COOPERATION TREATY

# TRANSLATION INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

(Chapter II of the Patent Cooperation Treaty)

(PCT Article 36 and Rule 70)

Applicant's or agent's file reference	I			
G281TJ	FOR FURTHER ACTION	See Form PCT/IPEA/416		
International application No.	International filing date (day/month/yea.	1 1		
PCT/JP2004/019688	22.12.2004	24.12.2003		
International Patent Classification (IPC) or nati				
B32B27/34 (2006.01),	C09J7/02(2006.01),	H01L21/304 (2006.01)		
Applicant				
TEIJIN LIMITED				
This report is the international prelin under Article 35 and transmitted to the		y this International Preliminary Examining Authority		
2. This REPORT consists of a total of	10 sheets, in	acluding this cover sheet.		
3. This report is also accompanied by A	NNEXES, comprising:			
a. (sent to the applicant and	to the International Bureau) a total of	Sheets, as follows:		
sheets of the descrip	otion, claims and/or drawings which have	been amended and are the basis for this report and/or see Rule 70.16 and Section 607 of the Administrative		
Instructions).	The state of the s	·		
		ity considers contain an amendment that goes beyond dicated in item 4 of Box No. I and the Supplemental		
	Bureau only) a total of (indicate type and	number of electronic carrier(s))		
(36.11.30 11.6 11.26.11.2	2 av com 2 av (mara 2 av 5, p a mara			
related thereto, in computer Section 802 of the Adminis		, containing a sequence listing and/or tables Supplemental Box Relating to Sequence Listing (see		
4. This report contains indications relati				
Box No. I Basis of the	report			
Box No. II Priority	report			
Por No III Non-establi	shment of opinion with regard to novelty	, inventive step and industrial applicability		
	ty of invention	, and an		
Box No. V Reasoned s		to novelty, inventive step or industrial applicability;		
citations an	d explanations supporting such statement			
Box No. VI Certain doc	uments cited			
Box No. VII Certain def	ects in the international application			
Box No. VIII Certain observations on the international application				
Date of submission of the demand	Date of completion	on of this report		
Name and mailing address of the IPEA/JP	Authorized office	er en		
Facsimile No.	Telephone No.			

International application No.

PCT/JP2004/019688

Вох	No. I		Basis of the report			
1.			to the language, this report is based on the internatio	nal application in the language in	which it	was filed, unless otherwise
			eport is based on translations from the original langua is the language of a translation furnished for the purp			
		닏	international search (Rule 12.3 and 23.1(b))			
		<u></u>	publication of the international application (Rule 12.4	)		
			international preliminary examination (Rule 55.2 and/	or 55.3)		
2.	recei		to the elements of the international application, this fice in response to an invitation under Article 14 are			
		the int	ernational application as originally filed/furnished			
	$\boxtimes$	the de	scription:			
		pages	1-3,5,7-63			as originally filed/furnished
		pages'	4,6	received by this Authority on	06.10	.2005
		pages'	k	received by this Authority on		
	$\boxtimes$	the cla	ims:			
		nos.	2,3,5-29			as originally filed/furnished
		nos.*				y statement) under Article 19
		nos.*	1		06.10	.2005
		nos.*				
		the dr	awings:			
		sheets	-			as originally filed/furnished
		sheets				-
						, , , , , , , , , , , , , , , , , , ,
		sheets				
		a sequ	ence listing and/or any related table(s) - see Supplem	ental Box Relating to Sequence L	isting.	
3.	M	The a	mendments have resulted in the cancellation of:			
			the description, pages			
		$\boxtimes$	the claims, nos. 4			
			the drawings, sheets/figs			
		$\sqcup$	the sequence listing (specify):			
			any table(s) related to sequence listing (specify):			
4.			eport has been established as if (some of) the amend ave been considered to go beyond the disclosure as fil			
			the description, pages			
			the claims, nos.			
			the drawings, sheets/figs			
			the sequence listing (specify):			
			any table(s) related to sequence listing (specify):			
*	If ite	m 4 apj	olies, some or all of those sheets may be marked "sup	erseded."		

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Bo	x No. I	Lack of unity of invention	
l.		In response to the invitation to restrict or pay additional fees the applicant has:	
		restricted the claims.	
		paid additional fees.	
		paid additional fees under protest.	
		neither restricted the claims nor paid additional fees.	
2.	$\boxtimes$	This Authority found that the requirement of unity of invention is not complied with and chose, according to Rule 68.1, not to invite the applicant to restrict or pay additional fees.	:
3.	This	Authority considers that the requirement of unity of invention in accordance with Rules 13.1, 13.2 and 13.3 is:	
		complied with.	
	$\boxtimes$	not complied with for the following reasons:	
		The inventions set forth in claims 1 to 3 and 5	
		to 24 pertain to a multilayer member with a layered	
		structure that includes the layered member (I) set	
		forth in claim 1, wherein an adhesive layer (B) has	
		been formed on one side or on both sides of the base	
		layer (A).	
		The inventions set forth in claims 25 to 29	
		pertain to the method for the production of multilayer	
		members which is set forth in claim 25, wherein the	
		outer surface of layer (E) in layered member (III),	
		which comprises a layer (C) to be bonded, an adhesive	
		layer (B), a base layer (A), an organic protective	
		layer (D) and a layer (E) to be processed, is	
		subjected to a process for converting said layer (E)	
		into a layer (E'); the resulting layered member is	
		subjected to a heat treatment; and then the layered	
		member (I) that comprises layer (C), layer (A) and	
		layer (B) is removed in order to produce a layered	
		member that comprises layers (D) and $(E')$ .	
4.	Con	equently, this report has been established in respect of the following parts of the international application:	
	$\boxtimes$	all parts.	
		the parts relating to claims Nos.	

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Rox		nt under Article 35(2) with regard to novelty, inventive step or industrial applicability; mations supporting such statement	
1.	Statement		
	Novelty (N)	Claims 1-3, 5-29	_ YES
		Claims	_ NO
	Inventive step (IS)	Claims	YES
		Claims 1-3, 5-29	_
	Industrial applicability (IA)	Claims 1-3, 5-29	1250
	PP	Claims 1-3, 5-29  Claims	
			_
2.	Citations and explanations (Rule 7	, ·	
-	Document 1: JP	2-272077 A (Nitto Denko Corp.), 06	
	No	ovember 1990, claims; page 3, upper right	
	co	olumn to page 4, upper left column; and	
	pā	age 5, upper left column to lower left	
	co	olumn	
	Document 2: JP	5-105850 A (Sumitomo Bakelite Co., Ltd.),	
	27	7 April 1993, claims; industrial field of	
	th	ne invention; paragraphs [0014] to [0015];	
	ar	nd table 1	
	Document 3: JP	2003-37155 A (Mitsubishi Gas Chemical	
	Co	o., Inc.), 07 February 2003, claim 1 and	
	pā	aragraphs [0007], [0016], [0019], [0022]	
	ar	nd [0050] & US 2002/0127821 A1	
4	Document 4: The	e Society of Polymer Science, Japan,	
	Ko	obunshi ABC Kenkyukai Ed., Polymer ABC	
	Hā	andbook, Kabushiki Kaisha NTS, 01 January	
	20	001, pages 72 to 79	
	Document 5: JP	10-67851 A (Ube Industries, Ltd.), 10	
	Ma	arch 1998, claim 1 and table 1	
•	Document 6: JP	2003-192788 A (Mitsui Chemicals, Inc.),	
	0.9	July 2003, claim 1 and table 1	
	Document 7: JP	2000-159887 A (Kaneka Corp.), 13 June	
	20	000, claim 1 and table 1	
		· · · · · · · · · · · · · · · · · · ·	

Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

- Document 8: JP 2-142827 A (Mitsui Toatsu Chemicals, Inc.), 31 May 1990, page 1, lower right column, lines 10 to 15
  - Document 9: JP 61-9458 A (Mitsui Toatsu Chemicals, Inc.), 17 January 1986, page 2, upper right column, line 20 to lower left column, line 17
- Document 10: JP 10-1643 A (Sumitomo Bakelite Co., Ltd.),
  06 January 1998, claim 1 and paragraphs
  [0022] and [0023]
- Document 11: JP 63-221138 A (Kanegafuchi Chemical Ind.),

  14 September 1988, claims, examples and
  table 1 & US 1991/5070181 A1 & EP 0281923

  B1
- Document 12: JP 63-254130 A (Mitsubishi Electric Corp.),
  20 October 1988, examples
  - Document 13: JP 9-139558 A (Hitachi, Ltd.), 27 May 1997, paragraph [0037] and table 1

The inventions set forth in claims 1, 5, 6, 8 and 13 do not involve an inventive step in the light of documents 1 and 2, which are cited in the international search report, and documents 11 and 12, which are newly cited in the present report.

Document 1 does not mention the glass transition temperature of the first layer, which is a support film; however, said document (page 3, upper right column to page 4, upper left column) discloses a composition that is described as being a fully aromatic polyimide with a glass transition temperature of 350°C or higher in the description of the present application. Such being the case, document 1 can be said to disclose an invention

Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

wherein the first layer has a glass transition temperature of 350°C or higher.

In addition, document 1 does not mention the linear expansion coefficient of the first layer; however, it is a known fact that it is preferable for the base layer of layered adhesive films that are used in the same applications in the same technical field as the adhesive layer disclosed in document 1 to have a low linear expansion coefficient as well as superior dimensional stability characteristics (for example, refer to document 2). Thus, it is desirable for the adhesive material disclosed in document 1 to be dimensionally stabile, and therefore it is considered to be necessary to employ a support film that has a low linear expansion coefficient therein. Furthermore, fully aromatic polyimides that have a low linear expansion coefficient within the range set forth in claim 1 of the present application are well known, as disclosed in document 11 (claims, examples and table 1) or document 12 (examples) for example. Such being the case, it would have been easy for a person skilled in the art to conceive of employing a film configured from one of the abovementioned well-known fully aromatic polyimides with a low linear expansion coefficient as the fully aromatic polyimide film of the first layer of the invention disclosed in document 1 in order to improve the dimensional stability characteristics thereof.

The invention set forth in claim 1 does not involve an inventive step in the light of documents 2, 5 to 7 and 10, which are cited in the international search report, and documents 11 to 13, which are newly cited in the present report.

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Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

Document 2 discloses thermobondable tape configured from a heat-resistant base layer and an adhesive layer that comprises a fully aromatic polyimide with a glass transition temperature of 350°C or lower, and given the thermobondability of the tape, it is apparent that the heat-resistant base layer has a glass transition temperature higher than the glass transition temperature of the adhesive layer. Meanwhile, document 10 indicates that it is preferable to employ a polyimide resin with a glass transition temperature of 350°C or higher as the base material that is coated with an adhesive agent comprising a polyimide resin with a glass transition temperature of 350°C or lower. Furthermore, fully aromatic polyimide resins that have a glass transition temperature of between 80°C and 350°C are well known, as disclosed in document 7 (claim 1 and table 1) for example.

Therein, document 2 does not delimit a numerical range for the linear expansion coefficient of the base layer, but does indicate that a film with a low linear expansion coefficient is used in order to improve the dimensional stability characteristics of the base layer. In addition, the fully aromatic polyimide film with a low linear expansion coefficient and the fully aromatic polyamide film with a low linear expansion coefficient from the invention set forth in claim 1 of the present application, which are configured from resins which are described as having a glass transition temperature of 350°C or higher in the description of the present application, are well known, as disclosed in document 11, document 12 and document 13 (paragraph [0037] and table 1). Such being the case, it would have been easy for a

Box No. V

Reasoned statement under A rticle 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

person skilled in the art to conceive of employing the abovementioned well-known films that have a low linear expansion coefficient as the base layer of the thermobondable tape disclosed in document 2 in order to improve the dimensional stability characteristics thereof.

The inventions set forth in claims 2 and 3 do not involve an inventive step in the light of documents 1, 2, 5 to 7 and 10, which are cited in the international search report, and documents 11 to 13, which are newly cited in the present report.

Given the purpose of the invention disclosed in document 1, it would have been easy for a person skilled in the art to delimit the Young's modulus of the multilayer body with consideration of the product-mounting characteristics thereof.

The inventions set forth in claims 6 to 9, 13, 14, 16 and 17 do not involve an inventive step in the light of documents 2 and 4 to 10, which are cited in the international search report, and documents 11 to 13, which are newly cited in the present report.

It would have been easy for a person skilled in the art to conceive of employing the well-known fully aromatic polyimide films and fully aromatic polyamide films that are disclosed in documents 11 to 13 or the well-known fully aromatic polyimide resins and fully aromatic polyamide resins that are disclosed in document 4 as the resins with prescribed glass transition temperatures which constitute the heat resistant base material or the adhesive layer of the invention disclosed in document 2.

Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

The inventions set forth in claims 19 to 21 do not involve an inventive step in the light of documents 1, 2, 5 to 7 and 10, which are cited in the international search report, and documents 11 to 13, which are newly cited in the present report.

Document 2 discloses a feature wherein an adhesion layer that comprises an inorganic material such as silicon or a metal is laminated upon the adhesive layer.

The inventions set forth in claims 10 to 12, 15 and 18 do not involve an inventive step in the light of documents 2, 4, 5 to 7 and 10, which are cited in the international search report, and documents 11 to 13, which are newly cited in the present report.

It would have been easy for a person skilled in the art to conceive of employing the resin composition disclosed in document 4, which comprises a fully aromatic polyimide resin and a fully aromatic polyamide resin, in the adhesive layer of the invention disclosed in document 2.

The inventions set forth in claims 22 to 29 do not involve an inventive step in the light of documents 1 to 3, 5 to 7 and 10, which are cited in the international search report, and documents 11 to 13, which are newly cited in the present report.

Document 3 discloses a layered member that comprises a wafer, a multilayer resin film and a retaining substrate (claim 1), and further indicates that it is possible to provide a protective resin film to the circuit surface of the wafer (paragraph [0007]). Furthermore, document 3 also discloses a method for the production of thinned wafers by thinning the wafer in the abovementioned layered member and then removing the

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Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

multilayer resin film and the retaining substrate therefrom. Such being the case, it would have been easy for a person skilled in the art to conceive of using the adhesive film for processing semiconductor elements which is disclosed in document 1 or document 2 in the layered member and the method for the production of thinned wafers which are disclosed in document 3.